

Dual N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY			
	V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)
Channel-1	30	0.011 at V _{GS} = 10 V	10
		0.016 at V _{GS} = 4.5 V	8.2
Channel-2		0.0085 at V _{GS} = 10 V	14
		0.0095 at V _{GS} = 4.5 V	13

SCHOTTKY PRODUCT SUMMARY		
V _{DS} (V)	V _{SD} (V) Diode Forward Voltage	I _F (A)
30	0.53 V at 3 A	2

FEATURES

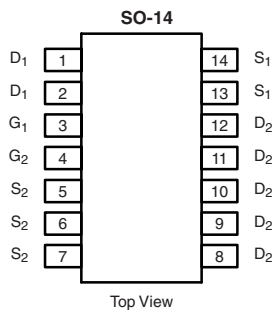
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



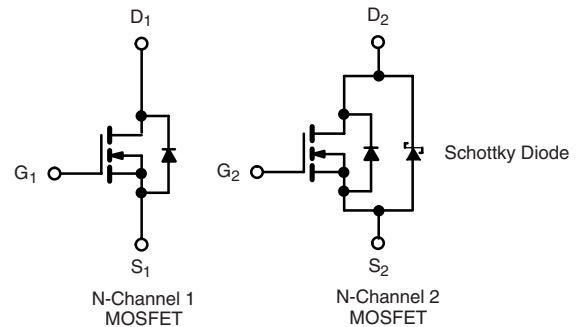
RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

- DC/DC Converters
 - Game Stations
 - Video Equipment



Ordering Information: Si4310BDY-T1-E3 (Lead (Pb)-free)
Si4310BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted							
Parameter	Symbol	Channel-1		Channel-2		Unit	
		10 s	Steady State	10 s	Steady State		
Drain-Source Voltage	V _{DS}	30				V	
Gate-Source Voltage	V _{GS}	± 20		± 20			
Continuous Drain Current (T _J = 150 °C) ^a	I _D	T _A = 25 °C	10	7.5	14	9.8	A
		T _A = 70 °C	8	6	11	7.8	
Pulsed Drain Current	I _{DM}	40		50			
Continuous Source Current (Diode Conduction) ^a	I _S	1.8	1.04	2.73	1.33	W	
Maximum Power Dissipation ^a	P _D	T _A = 25 °C	2	1.14	3.0		1.47
		T _A = 70 °C	1.28	0.73	1.9		0.94
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS									
Parameter		Symbol	Channel-1		Channel-2		Schottky		Unit
			Typ.	Max.	Typ.	Max.	Typ.	Max.	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	53	62.5	34	35	40	48	°C/W
	Steady State		92	110	70	72	76	93	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	35	42	17	24	21	26	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

MOSFET SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	Ch-1	1.0		3.0	V
			Ch-2	1.0		3.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	Ch-1			100	nA
			Ch-2			100	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$	Ch-1			1	μA
			Ch-2			100	
		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}, T_J = 85\text{ }^\circ\text{C}$	Ch-1			15	
			Ch-2			4000	
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} = 5\text{ V}, V_{GS} = 10\text{ V}$	Ch-1	20			A
			Ch-2	30			
Drain-Source On-State Resistance ^b	$R_{DS(on)}$		Ch-1		0.009	0.011	Ω
			Ch-2		0.0065	0.0085	
			Ch-1		0.013	0.016	
			Ch-2		0.0075	0.0095	
Forward Transconductance ^b	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 10\text{ A}$	Ch-1		30		S
			Ch-2		60		
Diode Forward Voltage ^b	V_{SD}	$I_S = 1.8\text{ V}, V_{GS} = 0\text{ V}$	Ch-1		0.76	1.1	V
		$I_S = 2.73\text{ V}, V_{GS} = 0\text{ V}$	Ch-2		0.485	0.53	
Dynamic^a							
Input Capacitance	C_{iss}	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	Ch-1	790	1580	2370	μF
			Ch-2	1530	3060	4590	
Output Capacitance	C_{oss}		Ch-1	145	290	435	μF
			Ch-2	300	600	900	
Reverse Transfer Capacitance	C_{rss}		Ch-1	70	140	210	μF
			Ch-2	115	225	340	
Total Gate Charge	Q_g	Channel-1 $V_{DS} = 15\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 10\text{ A}$	Ch-1		12	18	nC
			Ch-2		19	30	
Gate-Source Charge	Q_{gs}	Channel-2 $V_{DS} = 15\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 14\text{ A}$	Ch-1		5.3		nC
			Ch-2		10		
Gate-Drain Charge	Q_{gd}		Ch-1		4.3		nC
			Ch-2		5		
Gate Resistance	R_g	$f = 1\text{ MHz}$	Ch-1	0.90	1.8	2.7	Ω
			Ch-2	0.3	0.95	1.4	
Turn-On Delay Time	$t_{d(on)}$	Channel-1 $V_{DD} = 15\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong 1\text{ A}, V_{GEN} = 10\text{ V}, R_g = 6\text{ }\Omega$	Ch-1		13	20	ns
			Ch-2		17	26	
Rise Time	t_r	Channel-2 $V_{DD} = 15\text{ V}, R_L = 15\text{ }\Omega$ $I_D \cong 1\text{ A}, V_{GEN} = 10\text{ V}, R_g = 6\text{ }\Omega$	Ch-1		10	15	ns
			Ch-2		12	20	
Turn-Off Delay Time	$t_{d(off)}$		Ch-1		33	50	ns
			Ch-2		53	80	
Fall Time	t_f		Ch-1		10	15	ns
			Ch-2		17	26	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 1.8\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	Ch-1		25	40	ns
		$I_F = 2.73\text{ V}, di/dt = 100\text{ A}/\mu\text{s}$	Ch-2		31	50	

Notes:

a. Guaranteed by design, not subject to production testing.

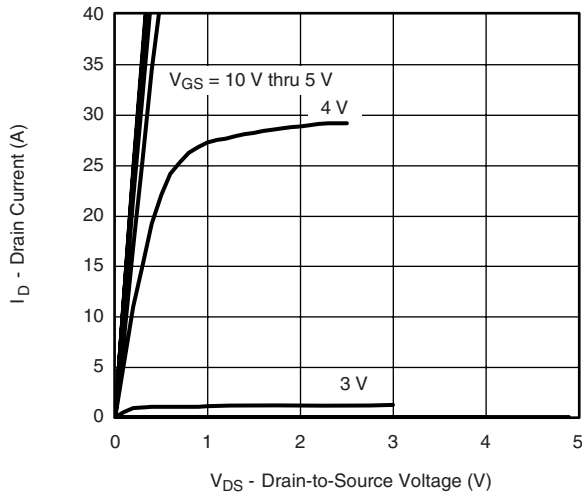
b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.



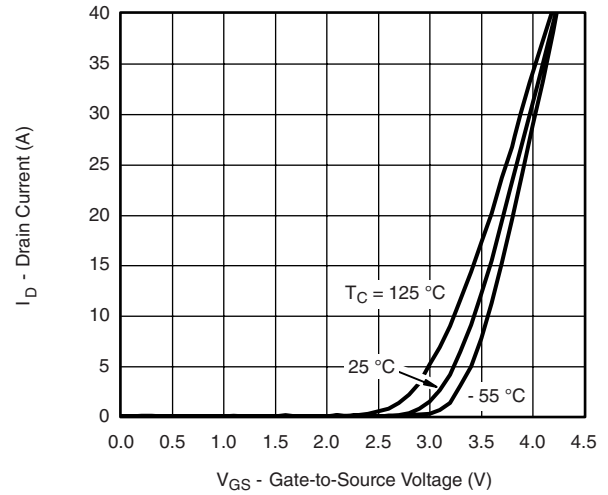
SCHOTTKY SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Forward voltage Drop	V_F	$I_F = 3\text{ A}$		0.485	0.53	V
		$I_F = 3\text{ A}, T_J = 125\text{ }^\circ\text{C}$		0.42	0.42	
Maximum Reverse Leakage Current	I_{rm}	$V_R = 30\text{ V}$		0.008	0.100	mA
		$V_R = 30\text{ V}, T_J = 75\text{ }^\circ\text{C}$		0.4	5	
		$V_R = 30\text{ V}, T_J = 125\text{ }^\circ\text{C}$		0.5	20	
Junction Capacitance	C_T	$V_R = 15\text{ V}$		102		pF

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

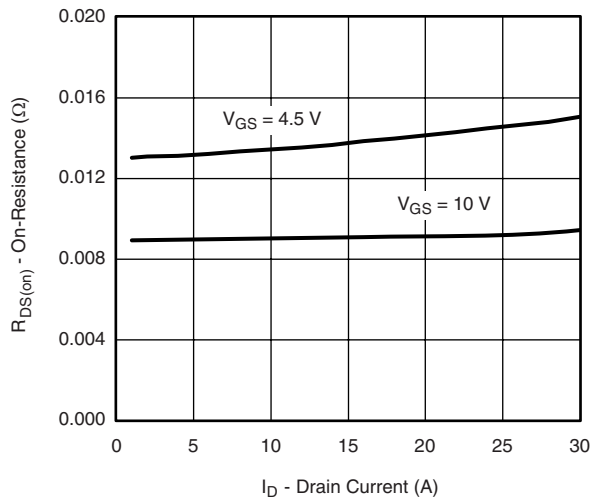
CHANNEL-1 TYPICAL CHARACTERISTICS $25\text{ }^\circ\text{C}$, unless otherwise noted



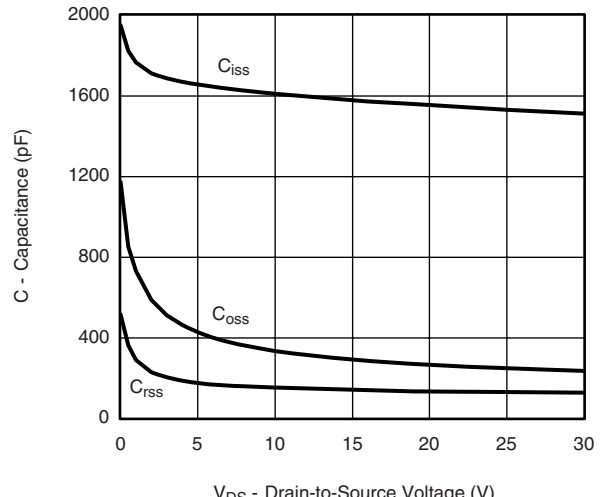
Output Characteristics



Transfer Characteristics

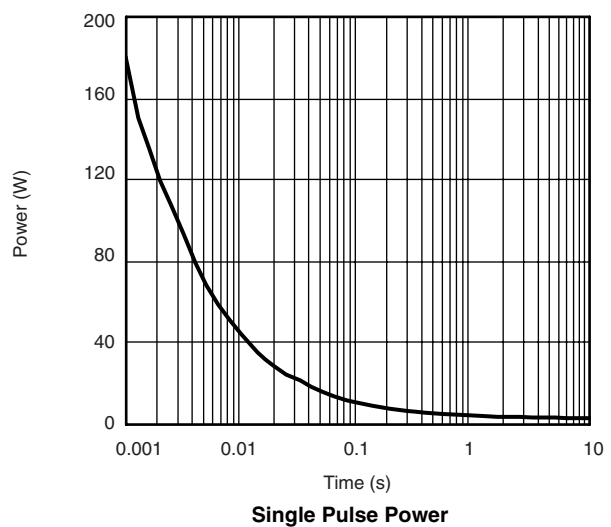
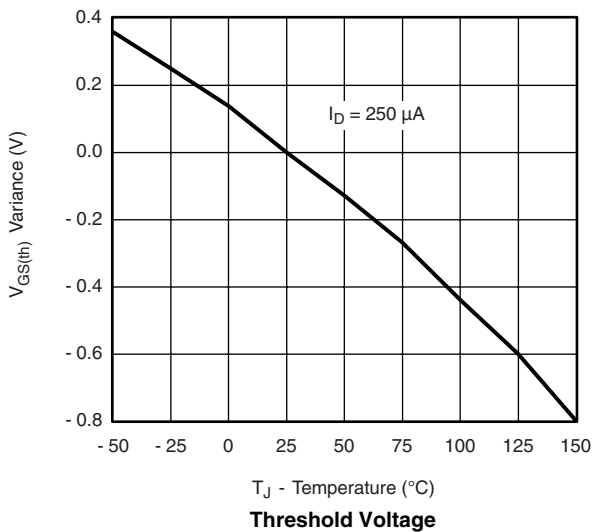
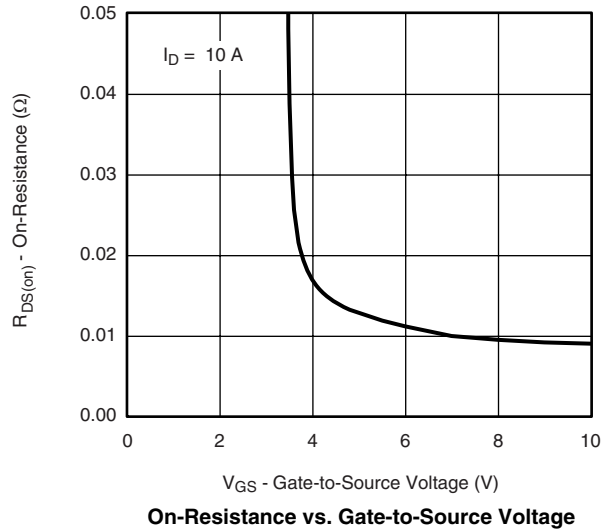
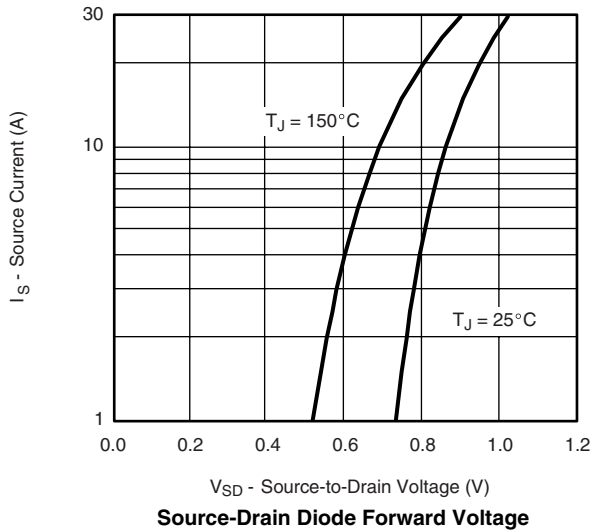
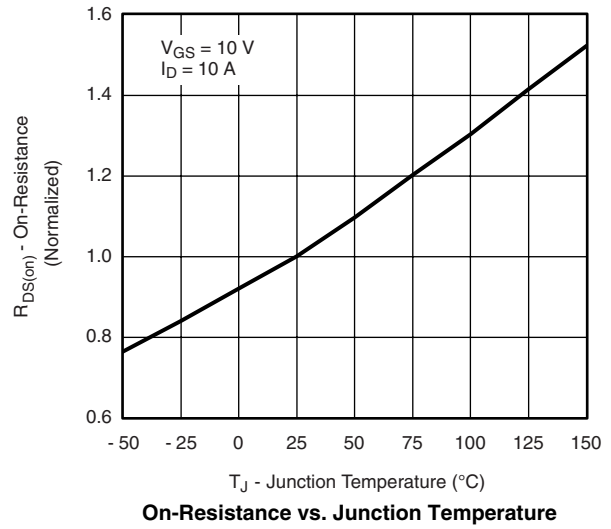
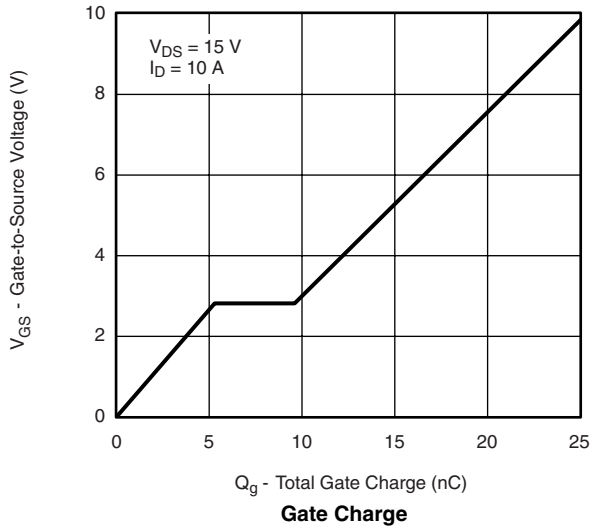


On-Resistance vs. Drain Current

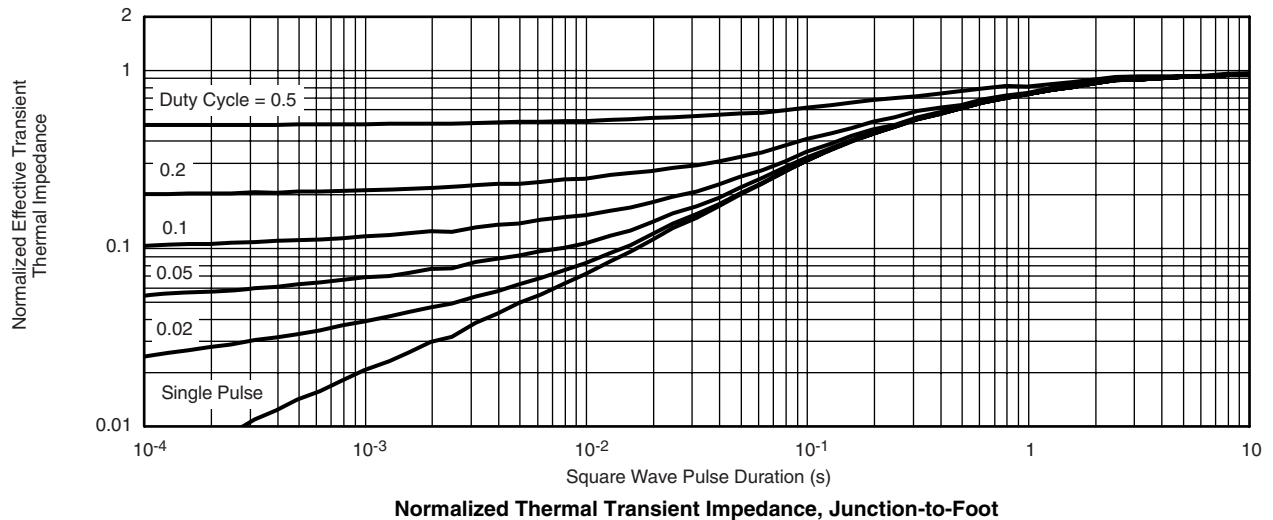
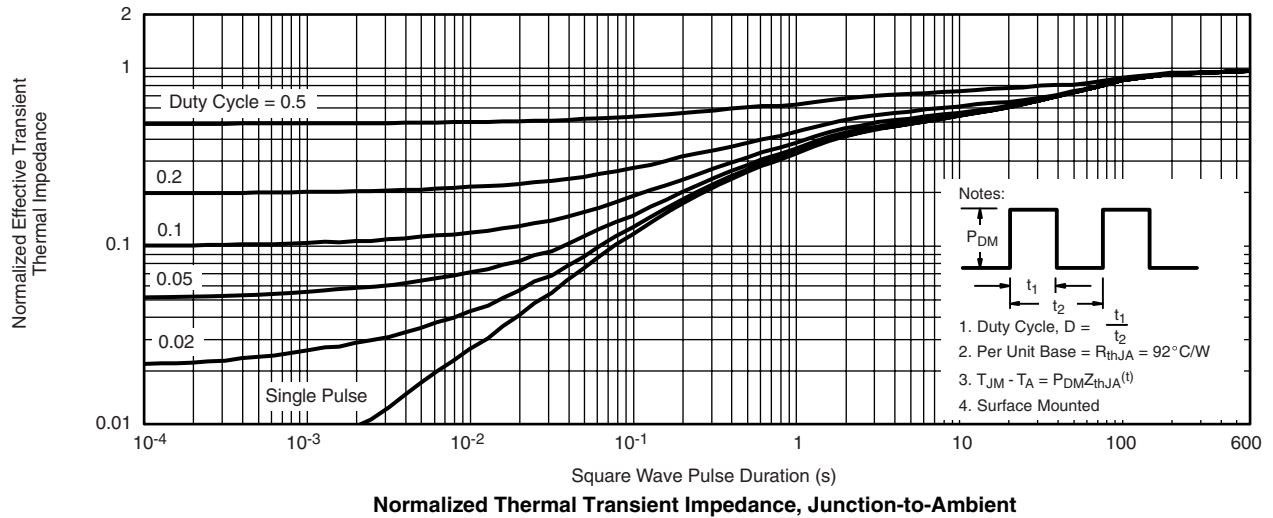
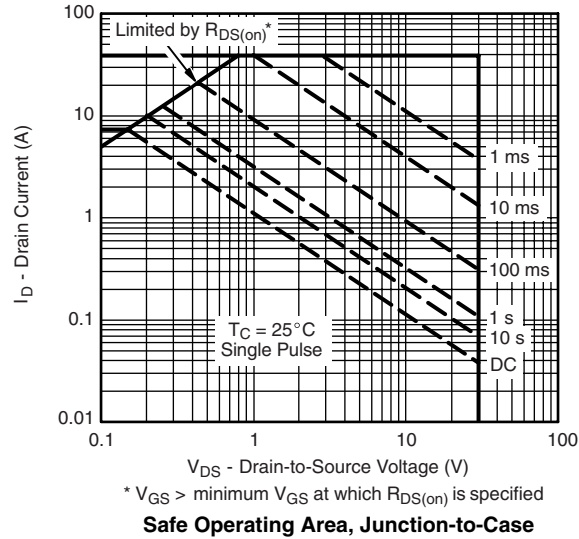


Capacitance

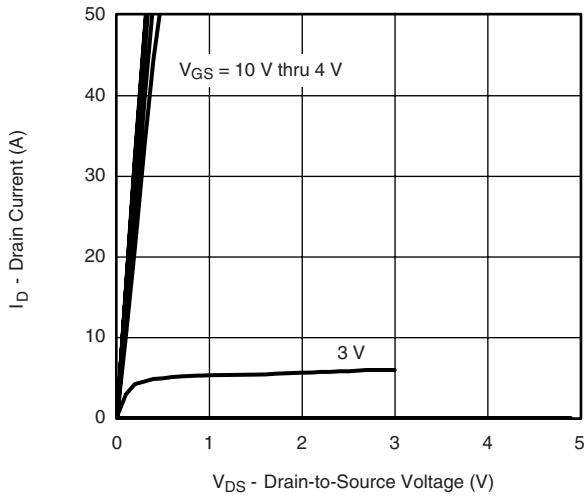
CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



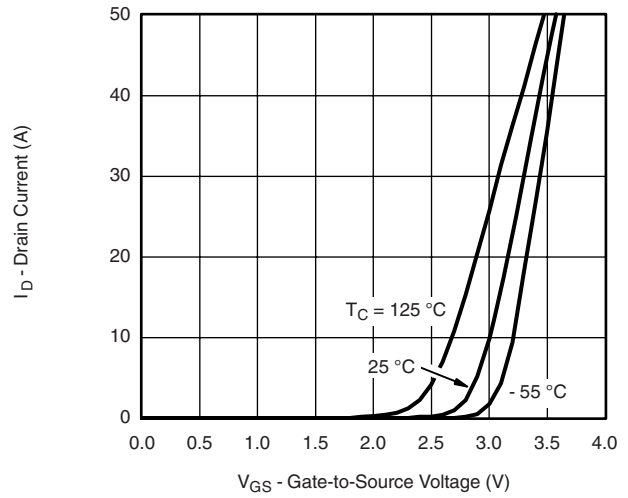
CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



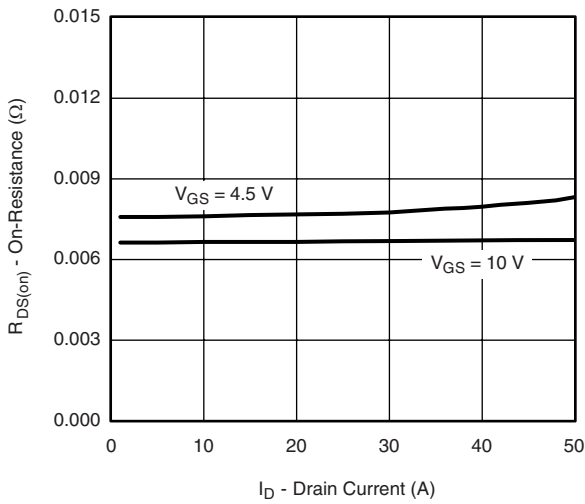
CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



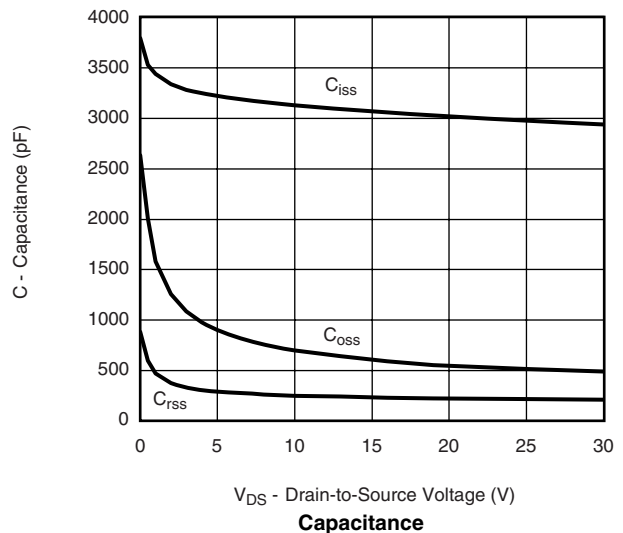
Output Characteristics



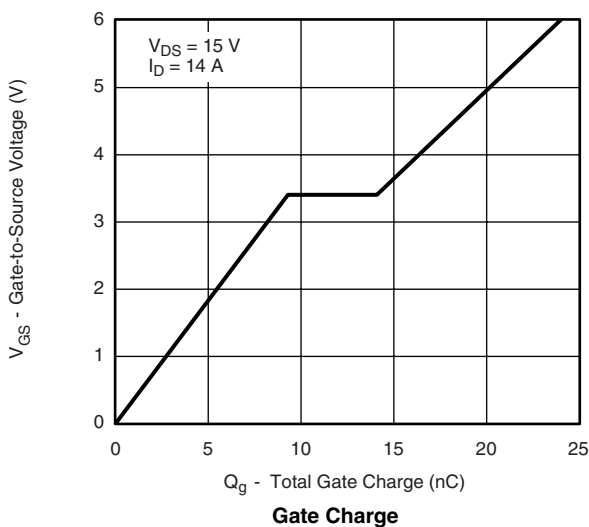
Transfer Characteristics



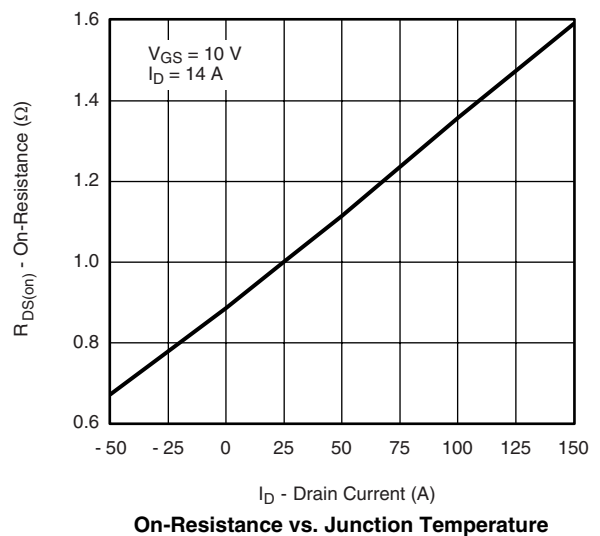
On-Resistance vs. Drain Current



Capacitance

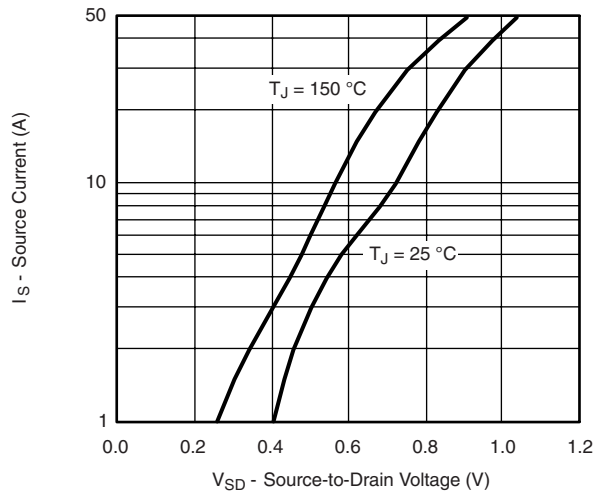


Gate Charge

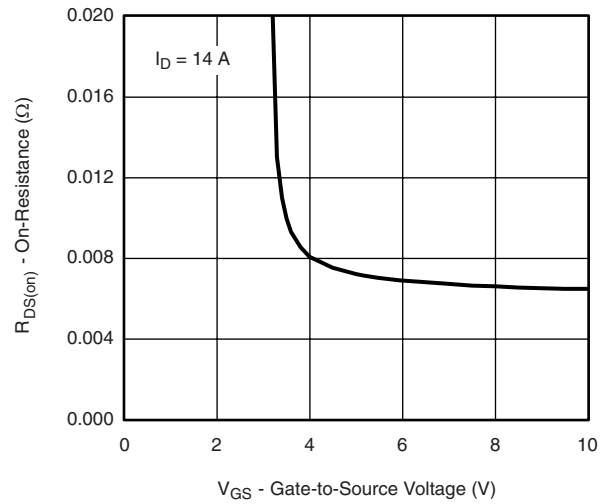


On-Resistance vs. Junction Temperature

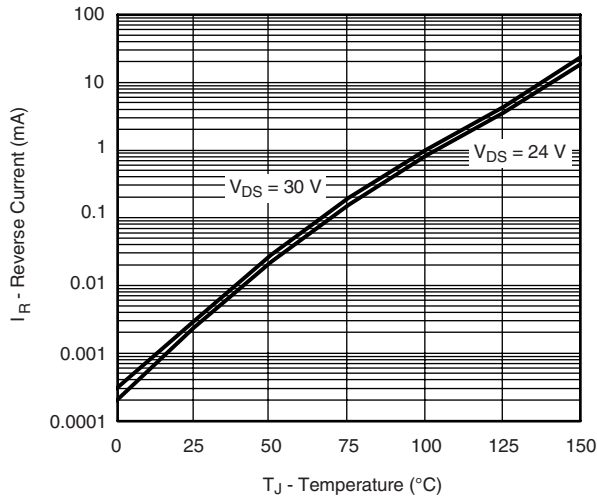
CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



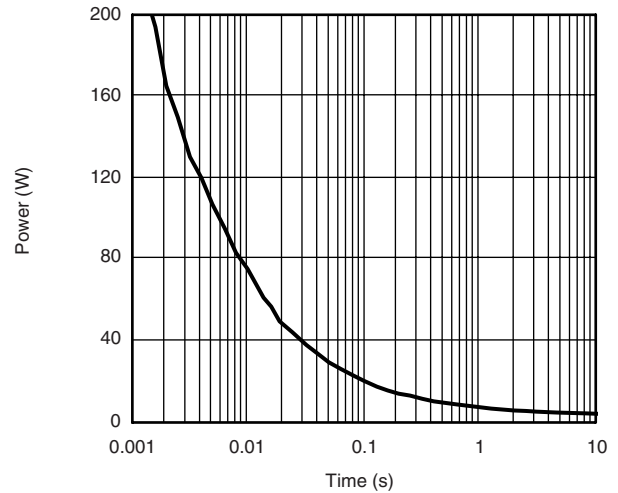
Source-Drain Diode Forward Voltage



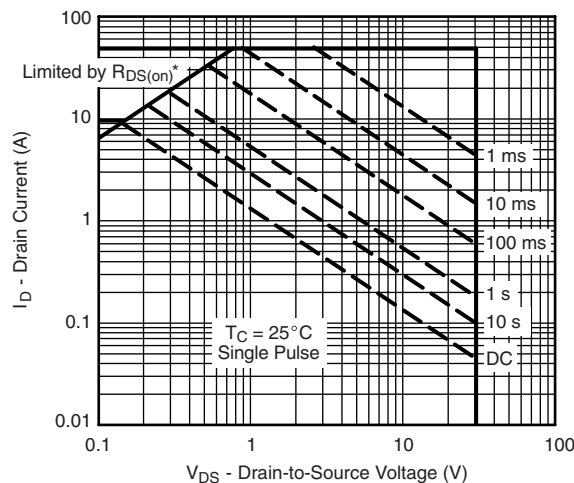
On-Resistance vs. Gate-to-Source Voltage



Reverse Current vs. Junction Temperature



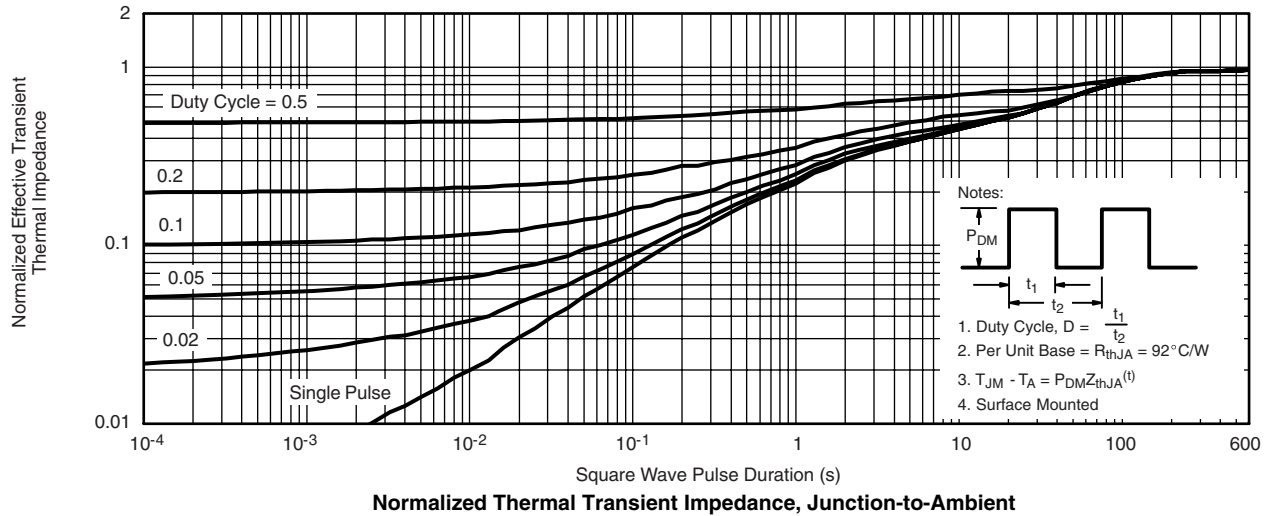
Single Pulse Power



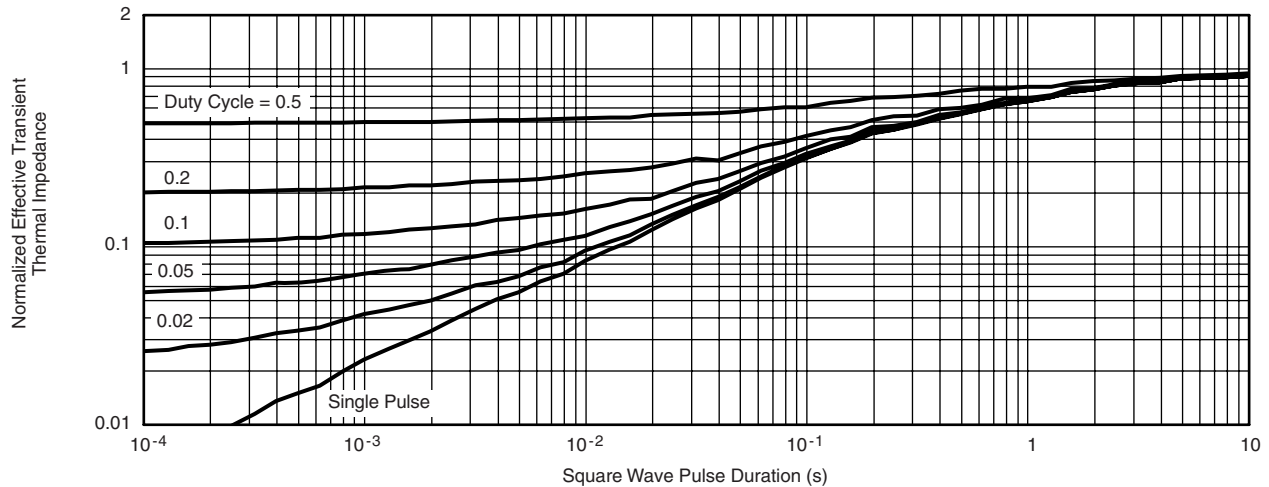
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Case

CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

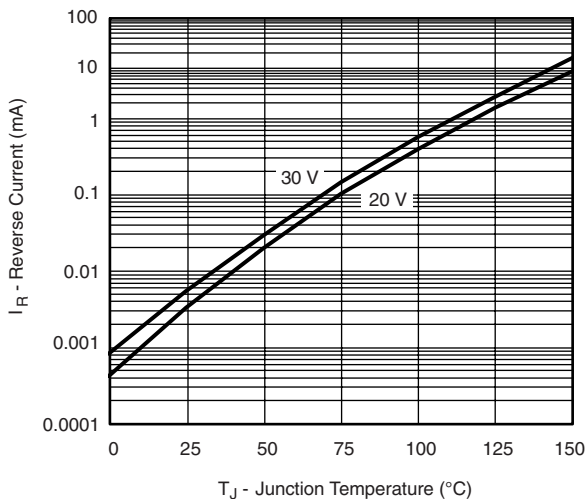


Normalized Thermal Transient Impedance, Junction-to-Ambient

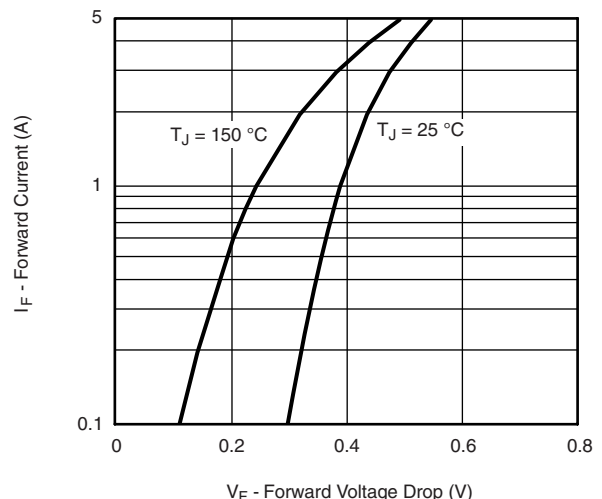


Normalized Thermal Transient Impedance, Junction-to-Foot

SCHOTTKY TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

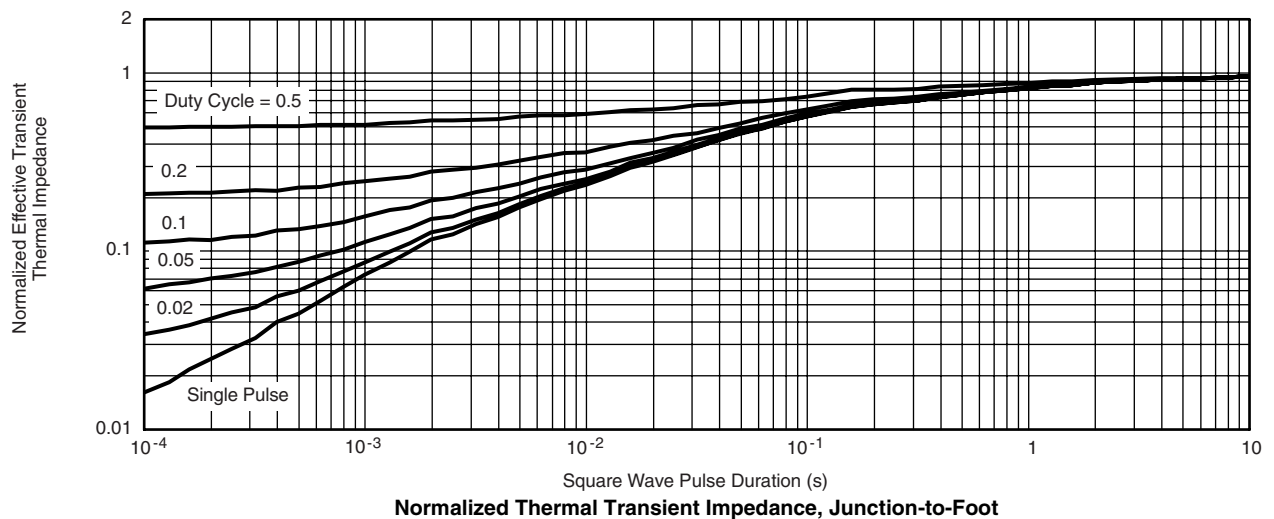
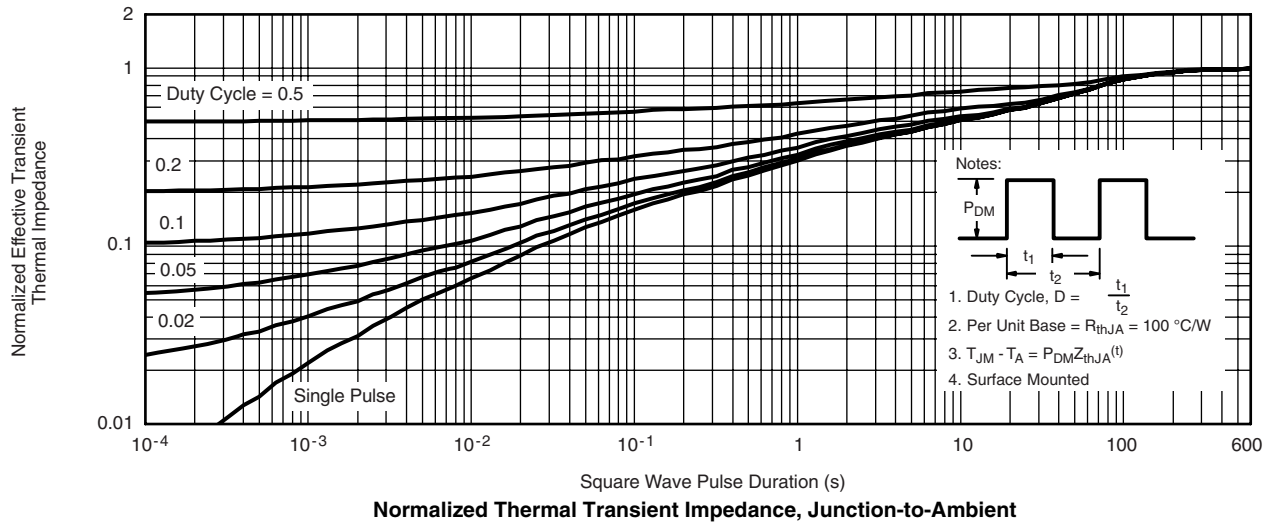
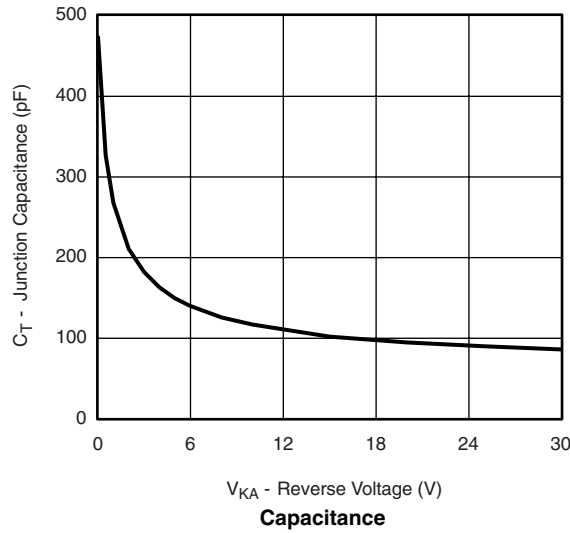


Reverse Current vs. Junction Temperature



Forward Voltage Drop

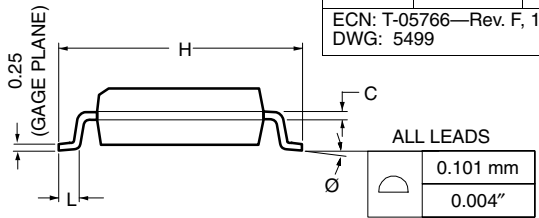
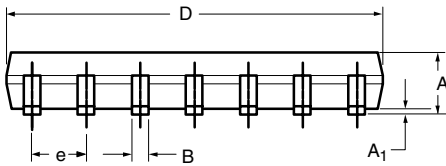
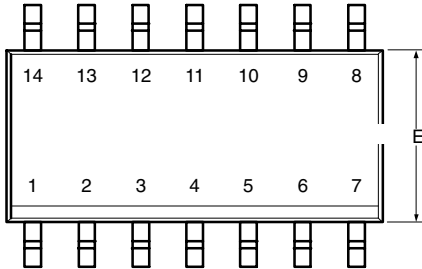
SCHOTTKY TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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SOIC (NARROW): 14-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A₁	0.10	0.20	0.004	0.008
B	0.38	0.51	0.015	0.020
C	0.18	0.23	0.007	0.009
D	8.55	8.75	0.336	0.344
E	3.8	4.00	0.149	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
L	0.50	0.93	0.020	0.037
Ø	0°	8°	0°	8°

ECN: T-05766—Rev. F, 19-Sep-05
DWG: 5499



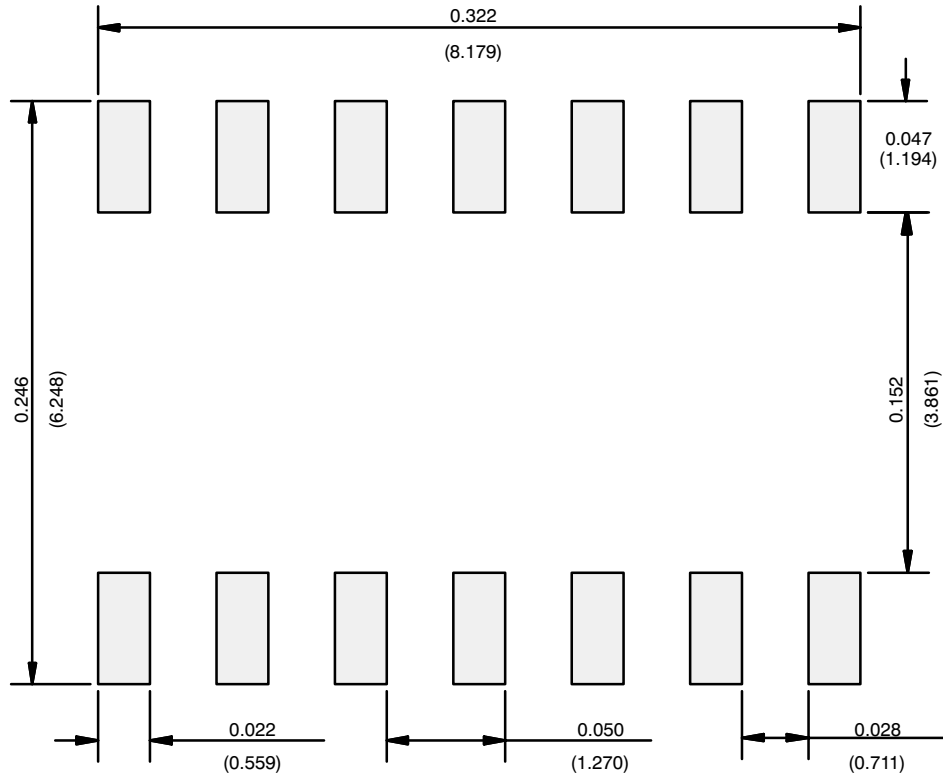
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RECOMMENDED MINIMUM PADS FOR SO-14



Recommended Minimum Pads
Dimensions in Inches/(mm)

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